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The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00259 for Sony GP compliant or per directive 2002/95/EC for RoHS compliant.

REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
AX1		NON-RELEASE REVISION	04/30/2009	Hank Hsu

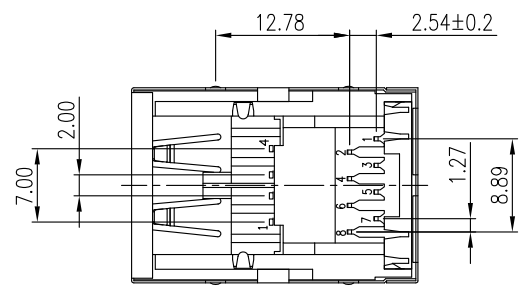
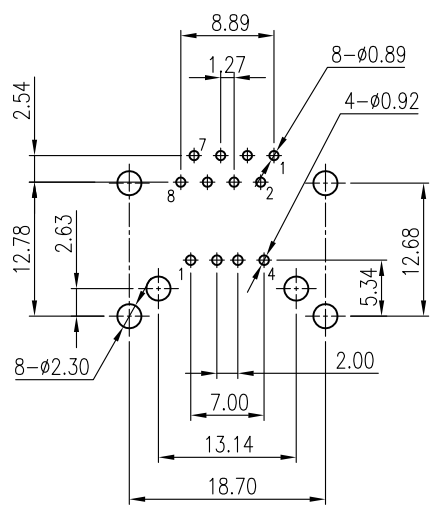
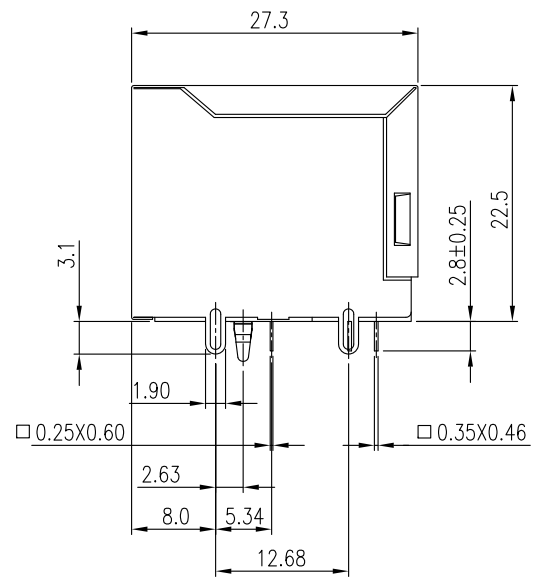
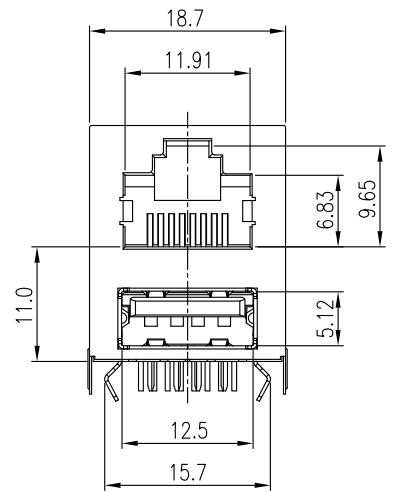
PRELIMINARY RELEASE
SUBJECT TO CHANGE

NOTES:

1. RJ MATERIAL:
 - HOUSING: HIGH TEMPERATURE THERMAL PLASTIC, UL94V-0, PBT, COLOR: BLACK.
 - COVER: HIGH TEMPERATURE THERMAL PLASTIC, UL94V-0, PBT, COLOR: BLACK.
 - TERMINAL: COPPER ALLOY.
 - SHELL: COPPER ALLOY.
- USB MATERIAL:
 - HOUSING: HIGH TEMPERATURE THERMAL PLASTIC, UL94V-0, PBT, COLOR: BLACK.
 - TERMINAL: COPPER ALLOY.
 - SHELL: SPCC.
2. RJ FINISH:
 - TERMINAL:
 - CONTACT AREA: SELECTED GOLD PLATING;
 - SOLDERING AREA: GOLD FLASH PLATING;
 - UNDER PLATING: NICKEL PLATING 50 μm THICKNESS MIN. OVERALL.
 - SHELL:
 - SOLDERING AREA: TIN PLATING 100 μm THICKNESS MIN.;
 - UNDER PLATING: NICKEL PLATING 50 μm THICKNESS MIN. OVERALL.
- USB FINISH:
 - TERMINAL:
 - CONTACT AREA: SELECTED GOLD PLATING;
 - SOLDERING AREA: TIN PLATING 100 μm THICKNESS MIN.;
 - UNDER PLATING: NICKEL PLATING 50 μm THICKNESS MIN. OVERALL.
 - SHELL:
 - SOLDERING AREA: TIN PLATING 100 μm THICKNESS MIN.;
 - UNDER PLATING: NICKEL PLATING 50 μm THICKNESS MIN. OVERALL.
3. PACKING IS PER AMTA PACKING SPECIFICATION PKS-0001.
4. THIS PRODUCT DOESN'T CONTAIN ENVIRONMENTAL HAZARDOUS PER DIRECTIVE 2002/95/EC FOR RoHS COMPLIANT.

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A
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PART NO. G71J21X000EU
CONTACT FINISH
0: GOLD FLASH
1: 6 μm GOLD
2: 15 μm GOLD
3: 30 μm GOLD

PCB LAYOUT (TOLERANCE ±0.05mm)

TOLERANCE		APPROVALS		DATE	TITLE		Amphenol®		
X.		DRAWN Roger Tsai		04/30/2009	MODULAR JACK, RJ45 STACKED OVER USB CONNECTOR, WITHOUT LED, DIP TYPE		Amphenol Corporation Amphenol Taiwan Corporation		
X.X	±0.30	CHECKED Daniel Hsieh		04/30/2009					
X.XX	±0.20	APPROVED Hank Hsu		04/30/2009					
X.XXX	±0.10	DWG TYPE CUST DWG		PROJECT CODE MJK	UNIT mm		SCALE NA	SIZE A3	PART No. G71J21X000EU
ANGULAR	±1°	UNLESS OTHERWISE SPECIFIED			SHEET 1 OF 1		DWG No. G71J21X000EU		REV. AX1

1 2 3 4 5 6 7 8